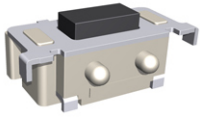


Operation: SMT/Tact Swtich & 贴片卧式 中小型轻触开关 带导位柱



**LTEM NO.: TS-1112E-T26 (Three D)**  
(L7.8mm×W3.5mm×H3.55mm TACT-SWITCH)



### Technical parameter

PROJECT	LEVEL	A[better product]		B[average product]	
<b>Electrical Properties</b>	Contact Rating	50mA, 24V DC			
	Initial Contact Resistance	30mΩ max.		50mΩ max.	
	Insulation Resistance	100MΩ min.500V DC	Skey/PD:	100MΩ min.300V DC	
	Withstand Voltage	500V AC for 1 minute		350 V AC for 1 minut	
	<b>Durable Performance</b>	There No Load	100,000 Cycles		75,000 Cycles
Rated Load		80,000 Cycles		50,000 Cycles	
	<b>Storage temp.</b>	-25℃~+75℃(Operating Temp: )			

贴片安装 SMT

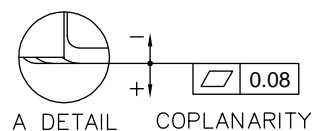
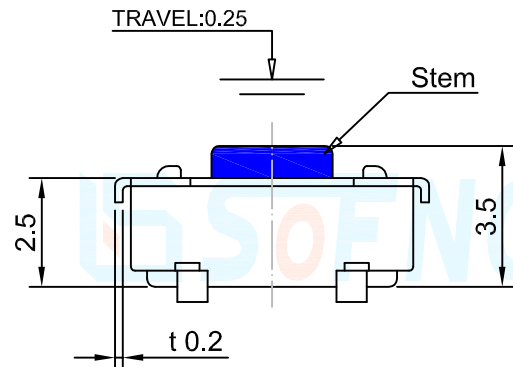
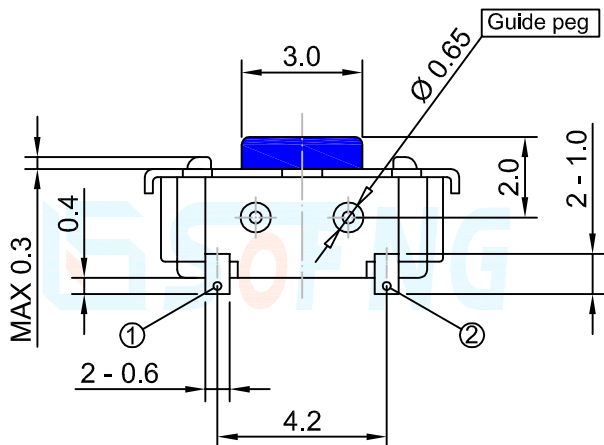
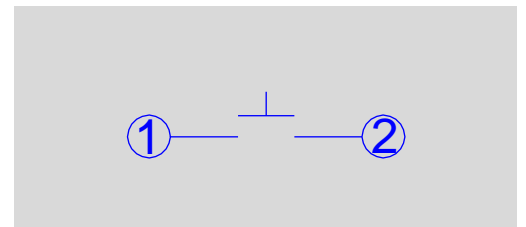
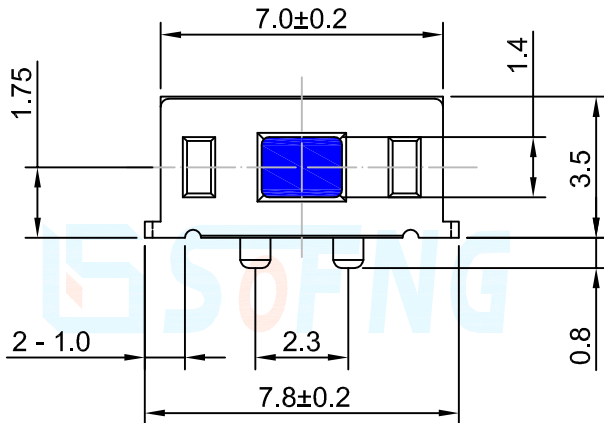
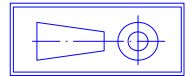
侧操作 LATERAL

精密部品 NICETY

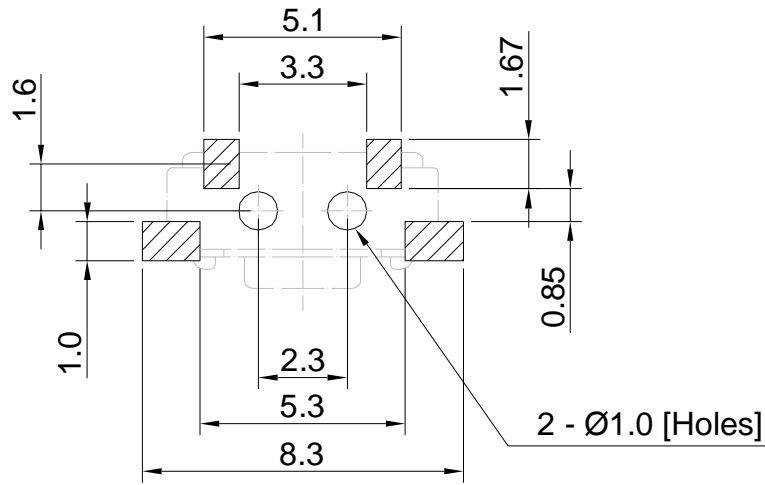
可靠 STABILIZE

適合環保 RoHS

Unit:mm



<b>Operating Force</b>	Inward	2. 6N. (1N. =100gram-force)	<b>Solder-ability (Max.)</b>
	Exiting	2. 0N. (1N. =100gram-force)	



Material declaration

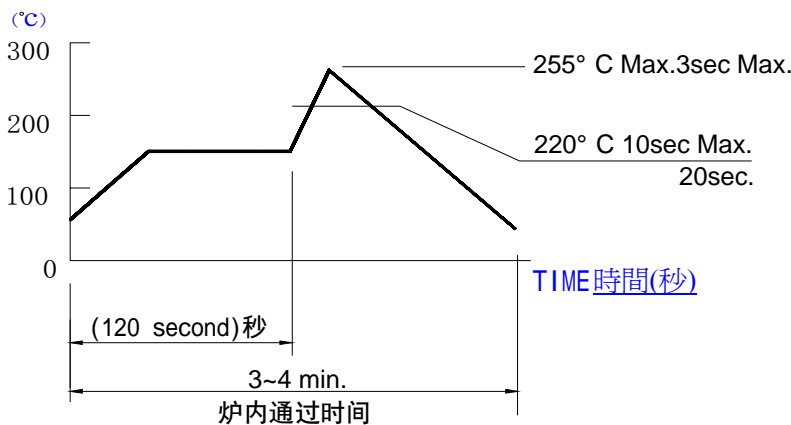


Material declaration

No.	NAME	Description
① A	拨柄	LCP (Black)热塑性
② B	基座	LCP (Black)热塑性
③ C	盖板	SUS 不锈钢 Q235-A
④ D	簧片	镀银&不锈钢 SUS304
⑤ E	嵌件	镀银&黄铜

Please practice according to below condition:

- (1) Preheat :150 °C 90-120s
- (2) Soldering heat : 255 °C Max 10S.
- (3) Immersion depth: Up to the surface of the board



■ 手焊接时

项目	条件
焊接温度	350°C max.
连续焊接时间	3s max.
焊剂斗容量	60W max.

■ 自动浸焊时

项目	条件
助焊剂附着量	不附着于零部件贴装面的程度
预热温度	印刷 电路板焊接面的周围温度 100°C max.
预热温度时间	60s max.
焊接温度	260°C max.
焊接浸渍时间	5s max.
焊接次数	2次以下

本品不屬於危害性廢棄物,須丟棄時可以委託回收商予以回收再生處理。  
Products do not belong to •

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